

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Hei Ming SHIU et al

§ Patent No.: 7205178 B2

§ Issue Date: April 17, 2007

§

Application No.: 10/807527

§ Examiner: Thanh Y. Tran

Filed: March 24, 2007

§ Group Art Unit: 2822

§

§ Docket No.: SC13154HP

Title: LAND GRID ARRAY PACKAGED DEVICE ANDMETHOD OF FORMING SAME

Certificate of Submission

I hereby certify that this correspondence is being submitted to the
U.S.P.T.O., Alexandria, VA.

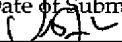
Addressed per 37 C.F.R. § 1.1(a) and deposited with the United
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5 July 2007

Date of Submission



Signature

Jeslyn GOH

Printed Name of Person Signing Certificate

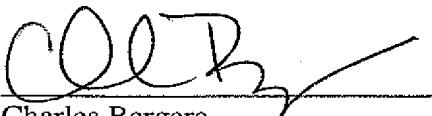
Commissioner for Patents
Alexandria, VA 22313

SUBMISSION OF CERTIFICATE OF CORRECTION

Dear Commissioner:

Enclosed, in duplicate, is a Certificate of Correction listing error(s) in the subject patent.
Please enter these corrections. Since the errors appear to be on the part of the United States
Patent Office, there should be no charge.

Respectfully submitted,


7/15/07

Date

Charles Bergere

Attorney for Applicant(s)

Registration No. 36,337

Telephone No. (512) 996-6839

Facsimile No. (512) 996-6854

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CERTIFICATE OF CORRECTION

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PATENT NO.: 7205178 B2
APPLICATION NO: 10/807527
DATE: 04/17/2007
INVENTOR(S): Hei Ming SHIU et al

It is certified that errors appear in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

In Column 6, Line 54, Claim No. 15:

Change "wherein-squashed" to - -wherein squashed- -

In Column 6, Line 56, Claim No. 15:

Change "s-aid" to - -said- -

MAILING ADDRESS OF SENDER

Freescale Semiconductor, Inc.
Law Department
7700 West Parmer Lane PL02
Austin, TX 78729